

EPS Webinar Series 2021

Advanced Packaging for Autonomous Driving

Date : 27-July-2021 (Tue)
Time : 10.00am – 11.00am
Platform : IEEE CISCO WebEx

E-certificates will be provided to participants

Dr Eu Poh Leng
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Title: Advanced Packaging for Autonomous Driving
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Platform: CISCO WebEx
Presenter: Dr. Eu Poh Leng

Presenter's Bio :

- Dr Eu Poh Leng has been with Motorola/Freescale/NXP Semiconductors Malaysia for 24 yrs and has been very actively involved in the development and introduction of new technology and new product in internal and external factories. She has published 65 technical papers and 4 journals externally, and owns 23 filed and 11 issued patents.

Abstract:

- Great business opportunities in many industries are made available due to the advancement in autonomous driving technology, driven by automotive megatrends. Architecting the autonomous car requires comprehensive system solutions with safety and security built in. Car electronics packaging are changing to meet the higher functional requirements. New package types emerges as a result of greater innovation. The future of packaging is definitely more exciting!

It is FREE! Enroll yourself and join us in this exciting webinar. See you there!
*E-certificates will be provided to all participants

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